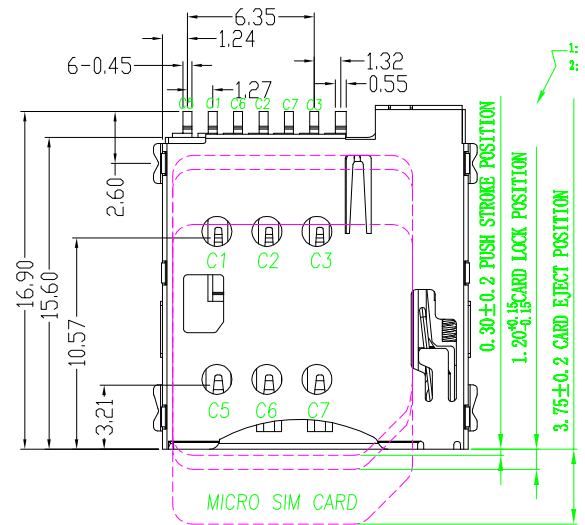
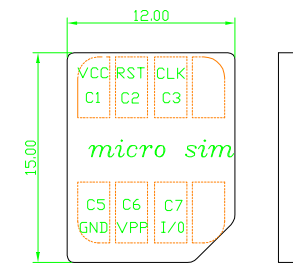
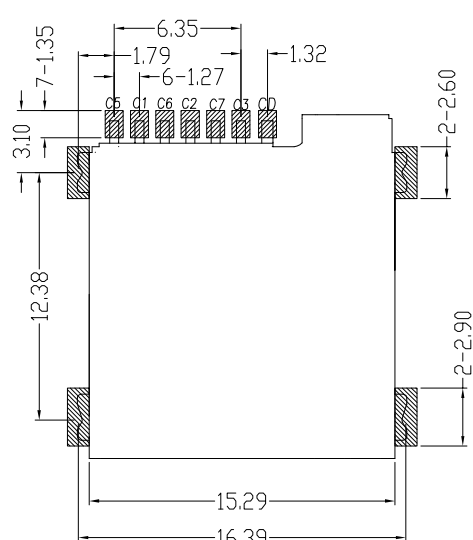
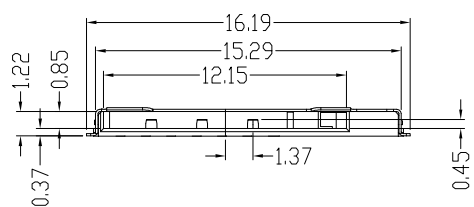
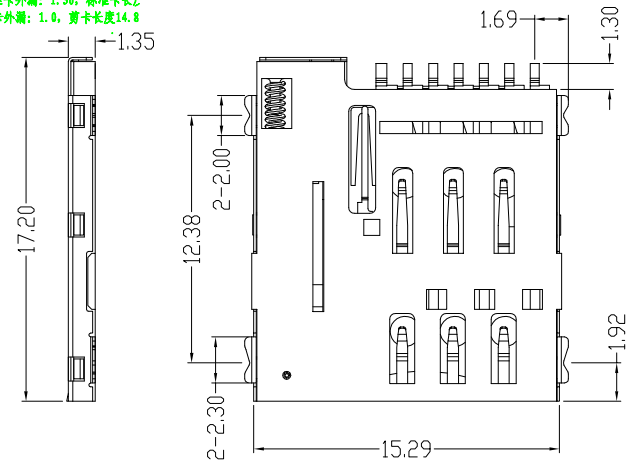


修 订	标 记	修 改 描 要	签 名	日 期
REV	MARK	REVISION DESCRIPTION	SIGNATURE	DATE
AO		NEW DWG		2016-03-12



1: 标准卡外漏: 1.30, 标准卡长L
2: 剪卡外漏: 1.0, 剪卡长度14.8



MICRO SIM CARD

PCB 焊盘区
下沉位区

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

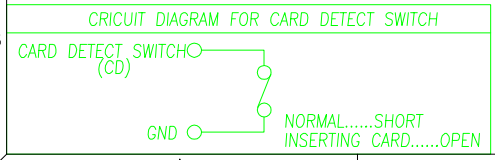
Specification


MATERIAL:
Insulator: High Temperature Thermoplastic, UL 94V-0,
Contact: Copper Alloy
SHELL: SUS

PLATING:
Contact: Plated 50u' Ni Overall Contact Au 1U
Shell: Plated 50u' Ni Overall
Plated 1u'Au Selective Contact Area

Electrical:
Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m max. Ω
Insulation Resistance:1000M min./500VDC
产品耐温温度: 260° C - C 84.70 - C 84.70 ± 5 C
Mating Cycles:3000Min Insertions

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出





深圳市华德共创科技有限公司
Shenzhen Huade co-create Technology Co.,LTD
电话: 0755-23304126 传真: 0755-29940187

-TOLERANCES- UNLESS OTHERWISE SPECIFIED 公差参数表		TITLE: MICRO SIM卡座PUSH 产品名称: 1.35H 带CD PIN	
X.X ±0.30	X.X* ±3°	APPD: 核准:	PART NO: 产品编号: K-DYX-003
X.XX ±0.20	X.XX* ±2°	CHECK: 校对: 王建业	DATE SCALE UNIT CODE NUMBER
X.XXX ±0.10	X.XXX* ±1°	DRAW: 绘图: 黄艳兰	2016-03-12 1:1 mm A001